Freescale Semiconductor
Advance Information

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Rev. 2.0, 11/2007

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MPC7410 RISC Microprocessor Hardware Specifications Addendum for the MPC7410*xxnnn*NE Series

This document describes part number-specific changes to recommended operating conditions and revised electrical specifications, as applicable, from those described in the general *MPC7410 Hardware Specifications* (Document No. MPC7410EC).

Specifications provided in this document supersede those in the *MPC7410 Hardware Specifications*, for the part numbers listed in Table A only. Specifications not addressed herein are unchanged. Because this document is frequently updated, refer to http://www.freescale.com or to your Freescale sales office for the latest version.

Note that headings and table numbers in this document are not consecutively numbered. They are intended to correspond to the heading or table affected in the general hardware specification. Part numbers addressed in this document are listed in Table A. For more detailed ordering information see Table 17.

Freescale Part Numbers Affected:

MPC7410RX400NE
MPC7410HX400NE
MPC7410VS400NE
MC7410VU400NE
MPC7410RX450NE
MPC7410HX450NE
MPC7410VS450NE
MC7410VU450NE

This document contains information on a new product. Specifications and information herein are subject to change without notice.

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Table A. Part Numbers Addressed by this Data Sheet

Freescale Part Number	Operating Conditions				Significant Differences from Hardware Specification
	CPU Frequency	Vdd	T_J (°C)	OVdd	
MPC7410RX400NE MPC7410HX400NE MPC7410VS400NE MC7410VU400NE	400 MHz	1.5V±50mV	0 to 105	1.8/2.5 V	Reduced core voltage to achieve lower power consumption. Removes 3.3V OVdd support. For all AC/DC specifications not mentioned in this document, please refer to the MPC7410(RX/HX/VS)400LE and MC7410VU400LE specifications in the general *MPC7410 Hardware Specifications*.
	450 MHz	1.8V ±100mV	0 to 105	1.8/2.5/3.3 V	The MPC7410(RX/HX/VS)400NE and MC7410VU400NE also fully conform to the MPC7410(RX/HX/VS)450LE and MC7410VU450LE specifications, respectively. Refer to the general *MPC7410 Hardware Specifications*.
MPC7410RX450NE MPC7410HX450NE MPC7410VS450NE MC7410VU450NE	450 MHz	1.5V±50mV	0 to 105	1.8/2.5 V	Reduced core voltage to achieve lower power consumption. Removes 3.3V OVdd support. For all AC/DC specifications not mentioned in this document, please refer to the MPC7410(RX/HX/VS)450LE and MC7410VU450LE specifications in the general *MPC7410 Hardware Specifications*.
	500 MHz	1.8V ±100mV	0 to 105	1.8/2.5/3.3 V	The MPC7410(RX/HX/VS)450NE and MC7410VU400NE also fully conform to the MPC7410(RX/HX/VS)500LE and MC7410VU500LE specifications, respectively. Refer to the general *MPC7410 Hardware Specifications*.

2 Features

This section summarizes changes to the features of the MPC7410 described in the *MPC7410 Hardware Specifications.*

- Bus interface
  - — Selectable interface voltages of 1.8 V, 2.5 V (3.3 V not supported)

4.1 DC Electrical Characteristics

Voltage to the L2 I/Os and processor interface I/Os are provided through separate sets of supply pins and may be provided at the voltages shown in Table 2.

Table 2. Input Threshold Voltage Setting

BVSEL Signal [3]	Processor Bus Input Threshold is Relative to:	L2VSEL Signal [3]	L2 Bus Input Threshold is Relative to:	Note
0	1.8 V	0	1.8 V	1
$\overline{\text{HRESET}}$	2.5 V	$\overline{\text{HRESET}}$	2.5 V	1, 2
1	Not Supported	1	2.5 V	1, 4, 5
HRESET	Not Supported	HRESET	Not Supported	—

Notes:
1. **Caution:** The input threshold selection must agree with the OVdd/L2OVdd voltages supplied.
2. To select the 2.5-V threshold option, BVSEL and/or L2VSEL should be tied to $\overline{\text{HRESET}}$ so that the two signals change state together. This is the preferred method for selecting this mode of operation.
3. To overcome the internal pull-up resistance, a pull-down resistance less than 250 ohms should be used.
4. Default voltage setting if left unconnected (internal pulled-up).
5. **Caution:** The XPC7410RXnnnNE does not support the default OVdd setting of 3.3 V. The BVSEL input must be tie either low or to $\overline{\text{HRESET}}$.

Table 3 provides the recommended operating conditions for the MPC7410 part numbers described herein.

Table 3. Recommended Operating Conditions

Characteristic		Symbol	Recommended Value	Unit
Core supply voltage		Vdd	1.5V ± 50mV	V
PLL supply voltage		AVdd	1.5V ± 50mV	V
L2 DLL supply voltage		L2AVdd	1.5V ± 50mV	V
Processor bus supply voltage	BVSEL = 0	OVdd	1.8V ± 100mV	V
	BVSEL = $\overline{\text{HRESET}}$	OVdd	2.5V ± 100mV	V
	BVSEL = HRESET or BVSEL = 1	OVdd	Not Supported	V
L2 bus supply voltage	L2VSEL = 0	L2OVdd	1.8V ± 100mV	V
	L2VSEL = $\overline{\text{HRESET}}$ or L2VSEL = 1	L2OVdd	2.5V ± 100mV	V
Input voltage	Processor bus and JTAG Signals	V_{in}	GND to OVdd	V
	L2 Bus	V_{in}	GND to L2OVdd	V
Die-junction temperature		T_j	0 to 105	°C
Note: These are the recommended and tested operating conditions. Proper device operation outside of these conditions is not guaranteed.				

Table 7 provides the power consumption for the MPC7410 part at the frequencies described herein.

Table 7. Power Consumption for MPC7410

	Processor (CPU) Frequency	Processor (CPU) Frequency	Unit	Notes
	400Mhz	450Mhz		
Full-On Mode				
Typical	2.92	3.29	W	1, 3
Maximum	6.6	7.43	W	1, 2,
Doze Mode				
Maximum	3.6	4.1	W	1, 2
Nap Mode				
Maximum	1.35	1.5	W	1, 2
Sleep Mode				
Maximum	1.3	1.45	W	1, 2
Sleep Mode—PLL and DLL Disabled				
Typical	0.6	0.6	W	1, 3
Maximum	1.1	1.1	W	1, 2

Notes:

1. These values apply for all valid processor bus and L2 bus ratios. The values do not include I/O Supply Power (OVdd and L2OVdd) or PLL/DLL supply power (AVdd and L2AVdd). OVdd and L2OVdd power is system dependent, but is typically <10% of Vdd power. Worst case power consumption for AVdd = 15 mw and L2AVdd = 15 mW.
2. Maximum power is measured at 105 °C and Vdd = 1.5V while running an entirely cache-resident, contrived sequence of instructions which keep the execution units, including AltiVec, maximally busy.
3. Typical power is an average value measured at 65 °C and Vdd = 1.5V in a system while running typical benchmarks.

9 Document Revision History

Table 16 provides a revision history for this Hardware Specification Addendum.

Table 16. Document Revision History

Revision	Date	Substantive Changes
2.0	11/16/2007	Updated document title to remove “RX” from part number since other non-RX package devices were added to this specification. Added MPC7410HX400NE, MPC7410VS400NE, MC7410VU400NE, MPC7410HX450NE, MPC7410VS450NE, and MC7410VU450NE devices to list on cover page and to Table A. Updated Table 17 to match corresponding table in *MPC7410 Hardware Specifications*
1.1	04/19/2005	Document template update
		Document ID change from MPC7410RXNEPNS for Part Number Specification to MPC7410ECS02AD for Hardware Specification Addendum.
1	10/2002	Minor formatting.
		Added Section 1.9 Document Revision History.
		Section 1.10.1 - added Table 17 - Part Marking Nomenclature.
0		Initial release

10 Ordering Information

10.1 Part Numbers Addressed by this Specification

Table 17 provides the ordering information for the MPC7410 part described in this document.

Table 17. Part Marking Nomenclature.

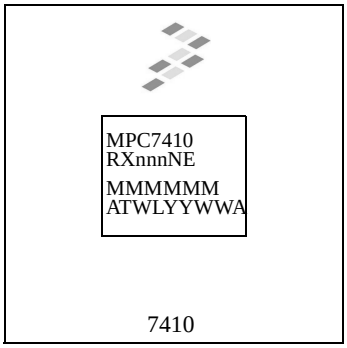
Mxx	7410	xx	*nnn*	N	E
Product Code	**Part Identifier**	**Package**	**Processor Frequency [1]**	**Application Modifier**	**Revision Level**
MPC	7410	RX = CBGA	400 450 500	N: 1.5 V ± 50 mV 0 to 105 °C	E: 1.4; PVR = 800C 1104
		HX = HCTE_CBGA VS = HCTE_LGA	400 450		
MC		VU = HCTE_CBGA (Lead Free C5 Solder Spheres)			

Notes:

1. Processor core frequencies supported by parts are addressed by this specification only. Parts addressed by other specifications may support other maximum core frequencies.

10.3 Part Marking

Parts are marked as the example shown in Figure 26.



Notes:
nnn is the speed grade of the part
MMMMMM is the 6-digit mask number
ATWLYYWWA is the traceability code
CCCCC is the country of assembly (this space is left blank if parts are assembled in the United States)

BGA

Figure 26. Freescale Part Marking for BGA Device

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How to Reach Us:

Home Page:
www.freescale.com

email:
support@freescale.com

USA/Europe or Locations Not Listed:
Freescale Semiconductor
Technical Information Center, CH370
1300 N. Alma School Road
Chandler, Arizona 85224
(800) 521-6274
480-768-2130
support@freescale.com

Europe, Middle East, and Africa:
Freescale Halbleiter Deutschland GmbH
Technical Information Center
Schatzbogen 7
81829 Muenchen, Germany
+44 1296 380 456 (English)
+46 8 52200080 (English)
+49 89 92103 559 (German)
+33 1 69 35 48 48 (French)
support@freescale.com

Japan:
Freescale Semiconductor Japan Ltd.
Headquarters
ARCO Tower 15F
1-8-1, Shimo-Meguro, Meguro-ku
Tokyo 153-0064, Japan
0120 191014
+81 2666 8080
support.japan@freescale.com

Asia/Pacific:
Freescale Semiconductor Hong Kong Ltd.
Technical Information Center
2 Dai King Street
Tai Po Industrial Estate,
Tai Po, N.T., Hong Kong
+800 2666 8080
support.asia@freescale.com

For Literature Requests Only:
Freescale Semiconductor
Literature Distribution Center
P.O. Box 5405
Denver, Colorado 80217
(800) 441-2447
303-675-2140
Fax: 303-675-2150
LDCForFreescaleSemiconductor
@hibbertgroup.com

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